# Frore Systems' AirJet®Mini G2 Powers Silent, Sustained AI Performance in the Qualcomm 2-in-1 Notebook and Mini PC Reference Designs.

*First unveiled at COMPUTEX, AirJet®Mini G2 can now be seen in real partner systems at CES — and has earned Frore Systems its third consecutive CES Innovation Award.*

**SAN JOSE, California – December 30, 2025** – Frore Systems today highlighted the continued momentum of **AirJet®Mini G2**, the company's most powerful solid-state active cooling chip to-date, showcased in real partner systems at CES, including the **Qualcomm Snapdragon X2 Elite 2-in-1 notebook and Mini-PC reference designs**.

First unveiled at **COMPUTEX 2025**, AirJet®Mini G2's rapid adoption by Qualcomm marks its transition from breakthrough technology to a **deployable platform design**, reflecting Frore's continued focus on translating thermal innovation into sustained, real-world performance as AI workloads increasingly move into compact, fanless devices.

AirJet®Mini G2 has also earned Frore Systems its **third consecutive CES Innovation Award**, underscoring continued industry recognition for solid-state active cooling technologies that remove thermal limits from next-generation AI systems.

## Building on Proven Commercial Deployments

AirJet®Mini G2 builds on a growing base of **commercially deployed AirJet Mini designs already shipping today**, including a **mission-critical communication device used by first responders**.

**AT&T's Sonim MegaConnect™**, the world's first **ultra-compact Power Class 1 5G mobile hotspot**, enabled by **AirJet® solid-state active cooling** is now shipping for use on **FirstNet®, built with AT&T**. Designed for frontline emergency response, MegaConnect delivers **six times the transmission power of standard hotspots** in a palm-sized, dustproof, water-resistant rugged form factor made possible by eliminating bulky thermal solutions and embracing **AirJet®**.

By enabling high sustained power in compact, rugged designs, AirJet® Mini has already proven itself in mission critical environments where **performance, reliability, and trust are non-negotiable**.

## AirJet® - Built for the Rise of AI Reasoning Models

As edge AI evolves from simple inference toward **AI reasoning models**, workloads are becoming more sustained and compute-intensive. These models spend more time "thinking," placing significantly greater thermal demands on edge devices.

AirJet®Mini G2 is designed specifically to support this shift. By increasing heat-removal capability by **50% over the original AirJet Mini**, while maintaining the same ultra-compact footprint, the AirJet®Mini G2 enables processors to sustain higher performance levels without throttling.

This advance aligns with **Frore's Law**, the company's long-term vision to **double thermal performance every two years** - keeping pace with AI compute.

### Sustained AI Performance Without Fans

In ultra-compact edge systems, thermal limits — not compute capability — are the primary constraint, and bulky heatsinks or thick noisy fans are not an option. AirJet®Mini G2 overcomes this thermal challenge with a chip just **~2.65 mm thin.**

At CES, Frore Systems is demonstrating AirJet®Mini G2 in a range of applications including:

- **Qualcomm 2-in-1 notebook reference design** enabling silent high performance in a ultra-thin device.
- **Qualcomm Mini-PC reference designs** unlocking sustained desktop-class performance in ultra-compact form factors.

These devices leverage AirJet®Mini G2 to maintain peak performance over time, rather than throttling after short bursts due to heat buildup.

### AirJet®Mini G2 Technical Highlights

- **Heat dissipation: 7.5 W** (50% increase over AirJet Mini G1)
- **Dimensions:** just **27mm × 41.5mm × 2.65 mm, supporting ultra-compact devices**
- **Back pressure: 1,750 Pa** (~10× higher than a fan), supporting dustproof, water-resistant
- **Noise level: 21 dBA**, enabling silent operation
- **Design:** solid-state, with no moving mechanical parts, delivering long life

AirJet®Mini G2 works by generating high-velocity pulsating air jets that efficiently eject heat from compact enclosures, enabling **sleek, light, ultra-compact, silent, vibration-free, dustproof, and water-resistant** device designs.

AirJet's small size and scalable nature means manufacturers can achieve significantly increased heat removal for higher sustained performance in the ultra-compact devices consumers demand. AirJet enhances performance across numerous devices from Notebooks, tablets, Mini-PCs, smartphones, 5G WiFi Hotspots, cameras and SSDs, to the tsunami of consumer and industrial IOT devices, and in markets as diverse as the datacenter, defense, and automotive industries.

## Third Consecutive CES Innovation Award

Frore Systems' **third consecutive CES Innovation Award** highlights growing recognition that **thermal technology has become a core performance enabler for edge AI**, not merely an afterthought.

*"AI reasoning models demand sustained performance, not short bursts," said Seshu Madhavapeddy, CEO and Founder of Frore Systems. "AirJet®Mini G2 removes the thermal barriers that have traditionally limited ultra-compact systems, allowing consumer products like super slim 2-in-1 notebooks and Mini-PCs to think longer, run faster, and operate in silence. This award validates our belief that solid-state active cooling is foundational to the next generation of ultra-compact edge AI devices."*

**Live Demonstrations at CES 2026:** Frore Systems will demonstrate edge AI devices with AirJet and Airjet PAK solid-state active air cooling featuring Industrial edge IoT platforms and consumer products, and Qualcomm Snapdragon X2 Elite compute reference platforms. Additional demonstrations include LiquidJet live at **CES 2026**, showcasing: LiquidJet coldplate performance for cooling **1,950W NVIDIA Rubin**, **600W/cm² extreme hotspot cooling**, and **single-reticle 1,200W ASIC cooling.**

**Experience the future of AI performance** in the Frore Systems Demonstration Room, **January 6–9**, Venetian Expo, Level 2, Room **2401B**, Las Vegas.

## About Frore Systems

Frore Systems is a pioneer in advanced thermal technologies that unleash performance across data centers and edge devices. The company's flagship solutions include **LiquidJet™**, a multi-stage 3D short-loop jetchannel liquid cooling coldplate for data centers delivering higher GPU performance, improved PUE and reduced TCO; and **AirJet®**, the world's first solid-state active cooling chip used in consumer, industrial, and IoT markets delivering higher performance in ultra-compact, silent, light, dustproof and water-resistant edge devices. Frore's patented cooling technologies are integrated into products from major OEMs and system builders worldwide. Frore Systems is headquartered in Silicon Valley, with manufacturing operations in Taiwan.

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